



# Status of Fast Orbit Feedback System of HEPS

(Cooperation work among all related systems)

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# Outline

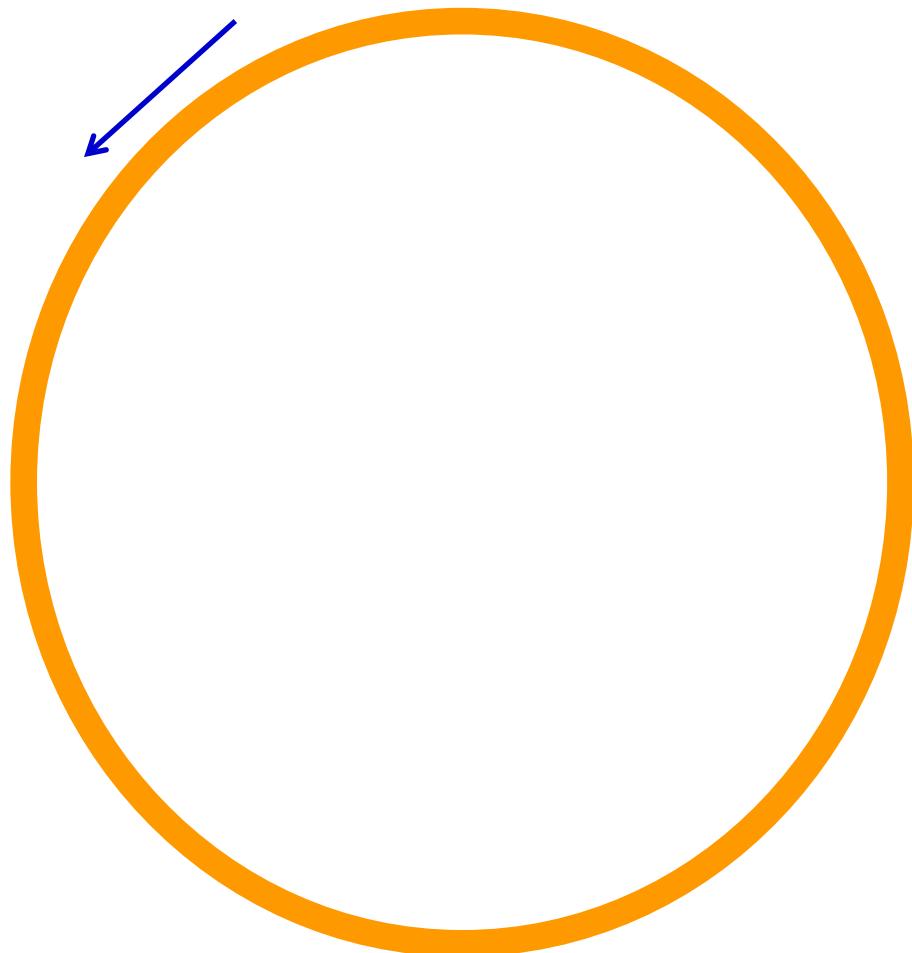
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- ◆ Introduction
- ◆ Requirement
- ◆ Architecture
- ◆ Hardware and Logic Design
- ◆ Schedule
- ◆ Summary



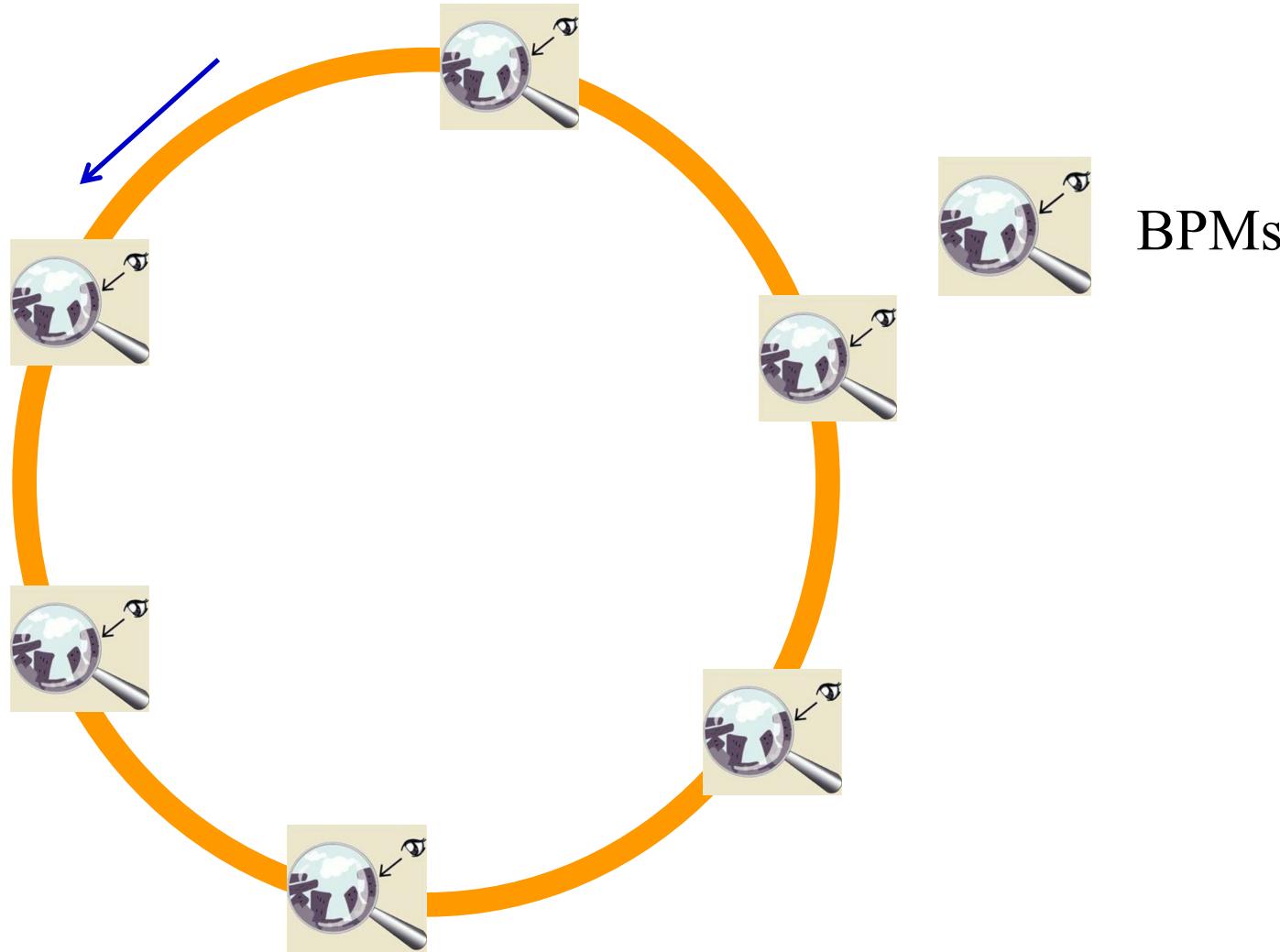
# Introduction of the FOFB

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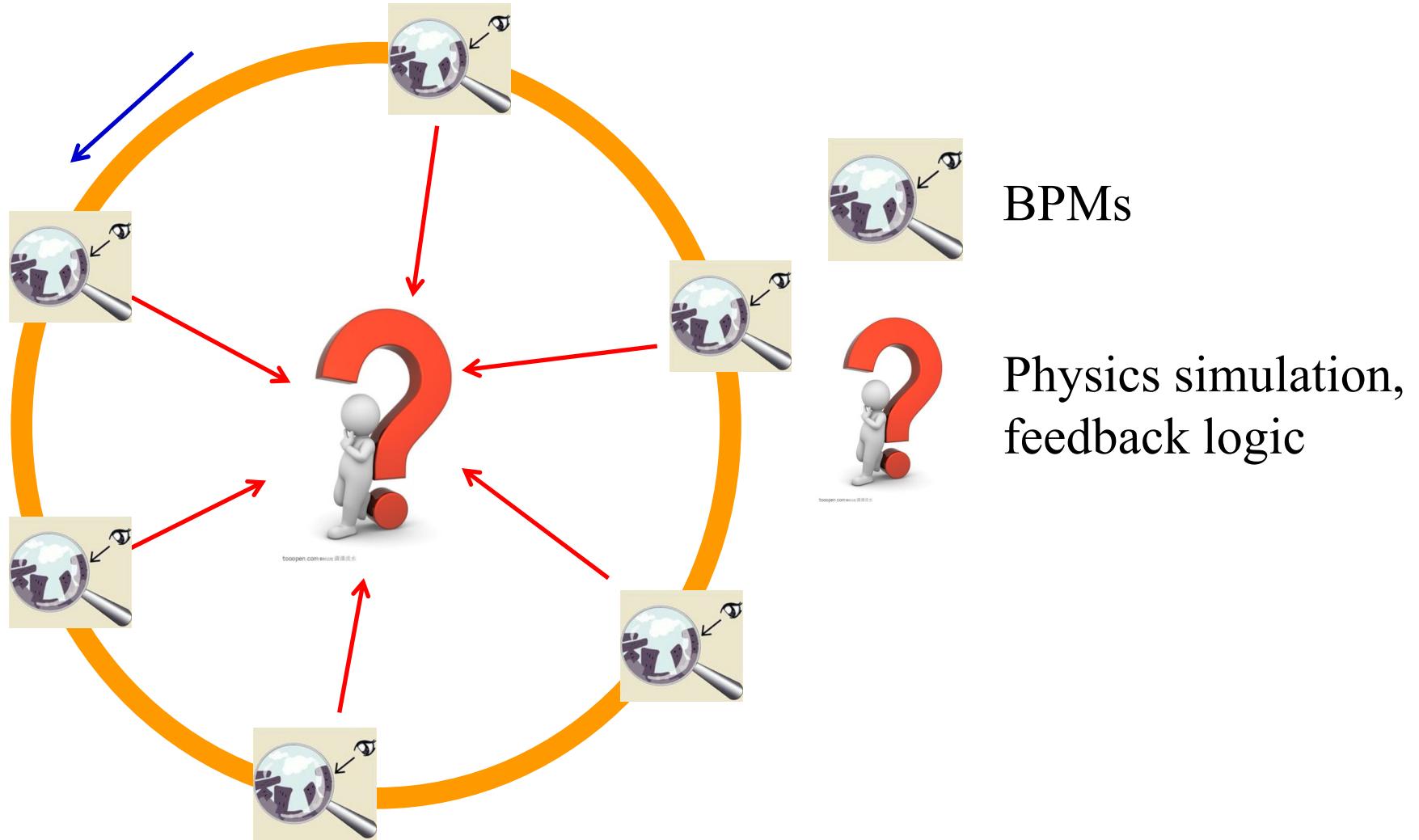


# Introduction of the FOFB



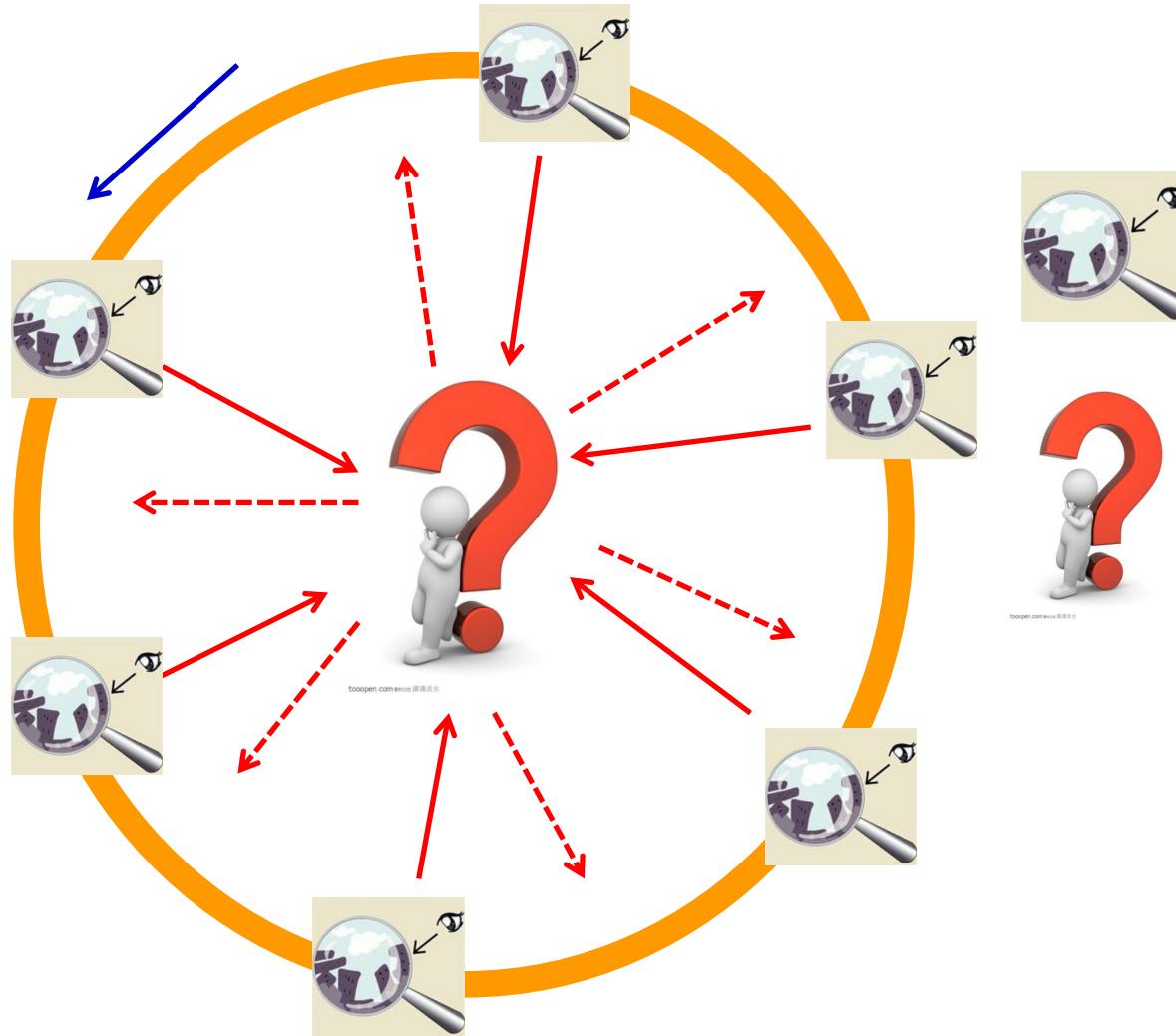


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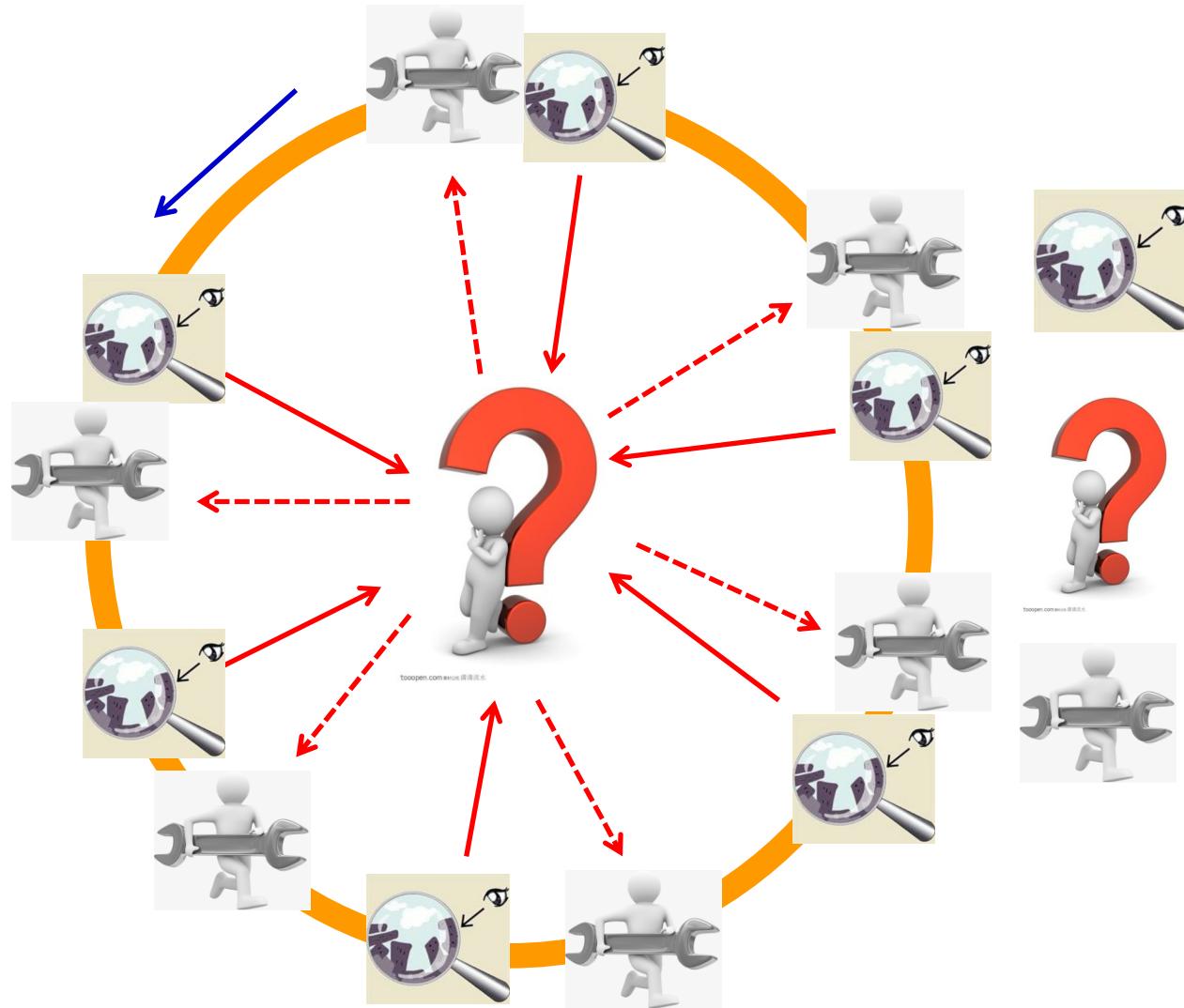


BPMs

Physics simulation,  
feedback logic



# Introduction of the FOFB



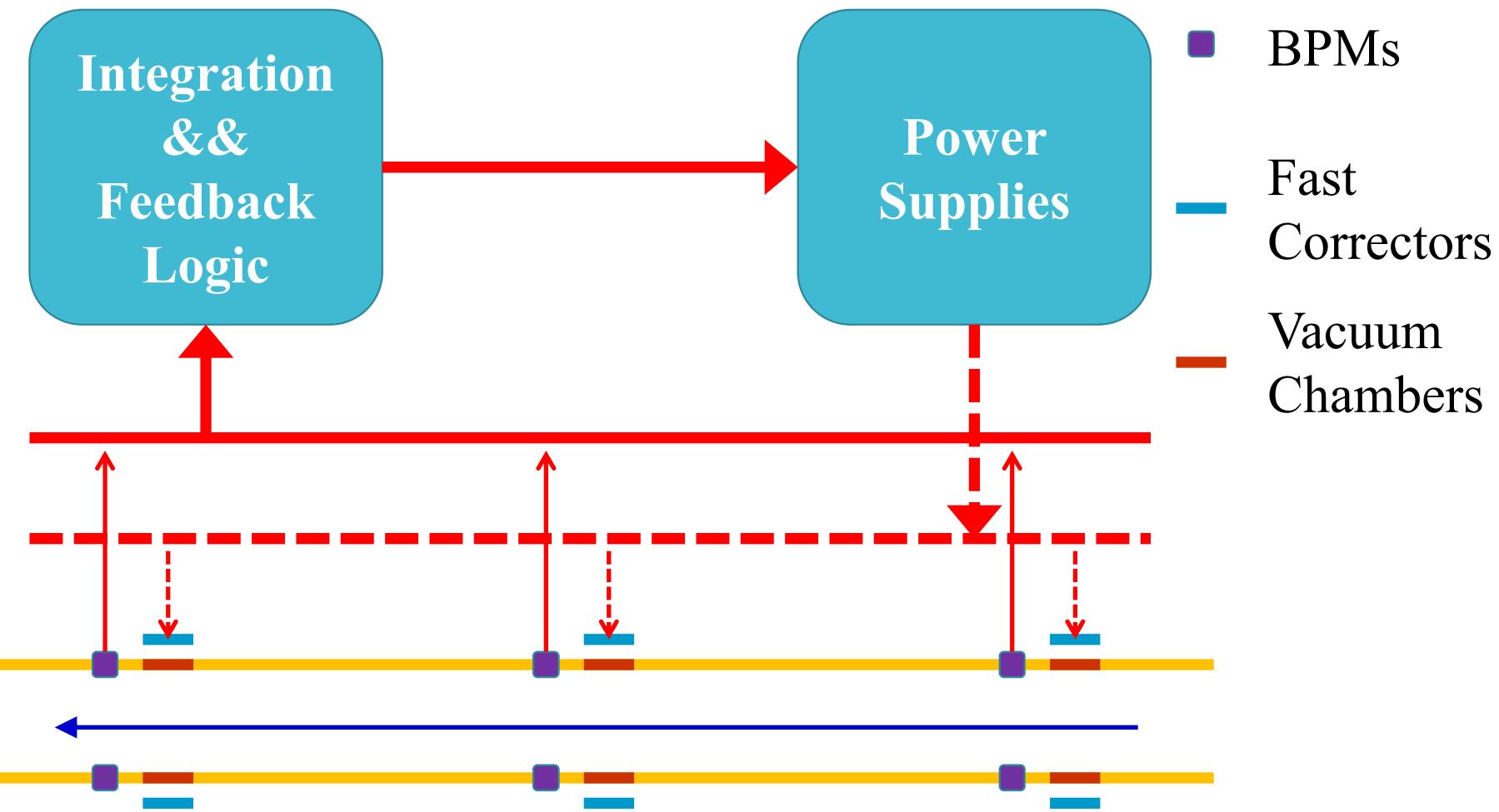
BPMs

Physics simulation,  
feedback logic

Power supplies,  
fast correctors,  
vacuum chambers



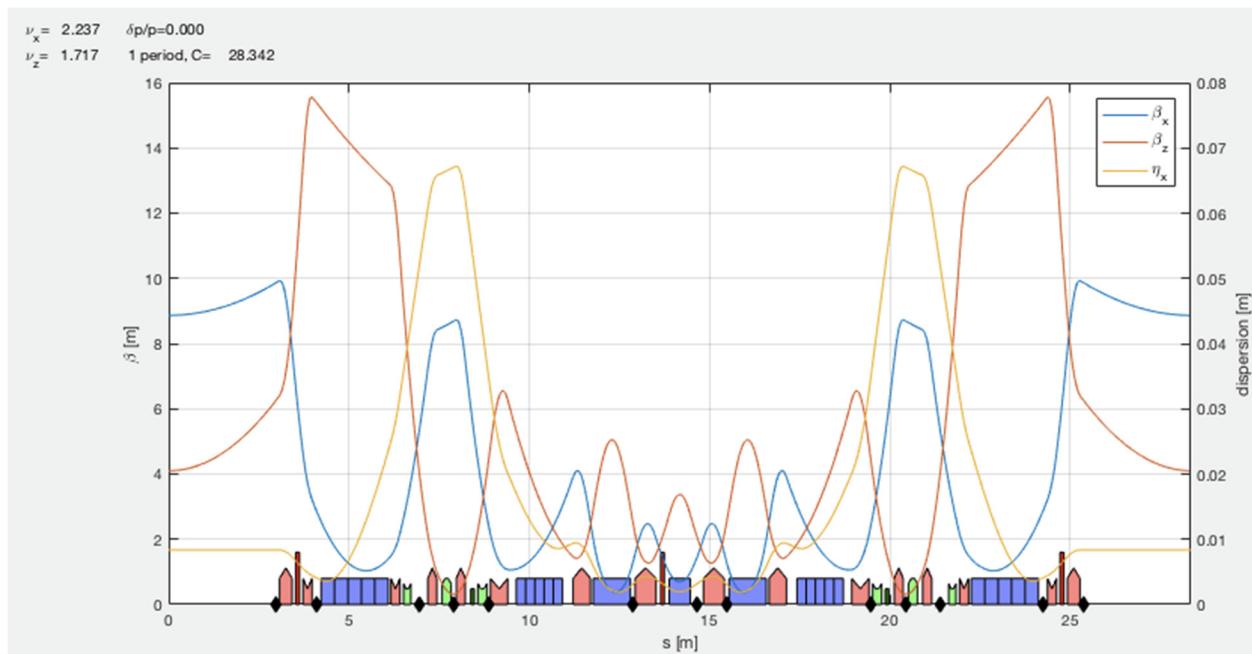
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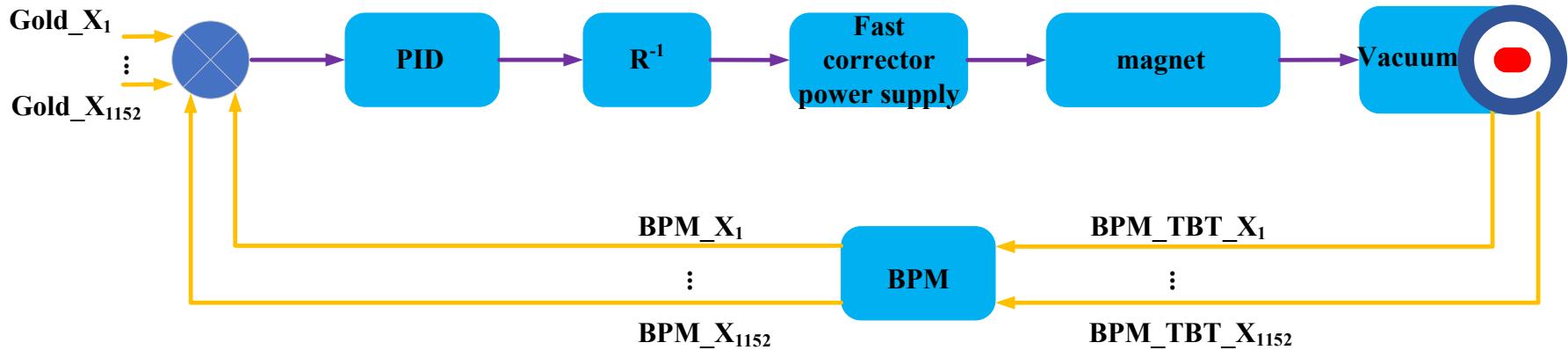
# Requirement of the FOFB

- 48 identical hybrid 7BAs cell
- 12 BPMs @ 4 fast correctors per cell





# Requirement of the FOFB



$$X_m = R * \theta_n \xrightarrow{\text{SVD}} \theta_n = R^{-1} X_m \quad R^{-1} = V Q \begin{pmatrix} \Sigma^{-1} & 0 \\ 0 & 0 \end{pmatrix} U^*$$

- $X_m$  为 BPM 测量束流实际轨道
- $R$  为  $m \times n$  响应矩阵
- $\theta_n$  为 快校正磁铁强度矢量

$$\begin{pmatrix} q_{11} & 0 & \cdots & 0 \\ 0 & q_{22} & \cdots & 0 \\ \vdots & \vdots & \ddots & \vdots \\ 0 & 0 & \cdots & 0 \end{pmatrix}$$

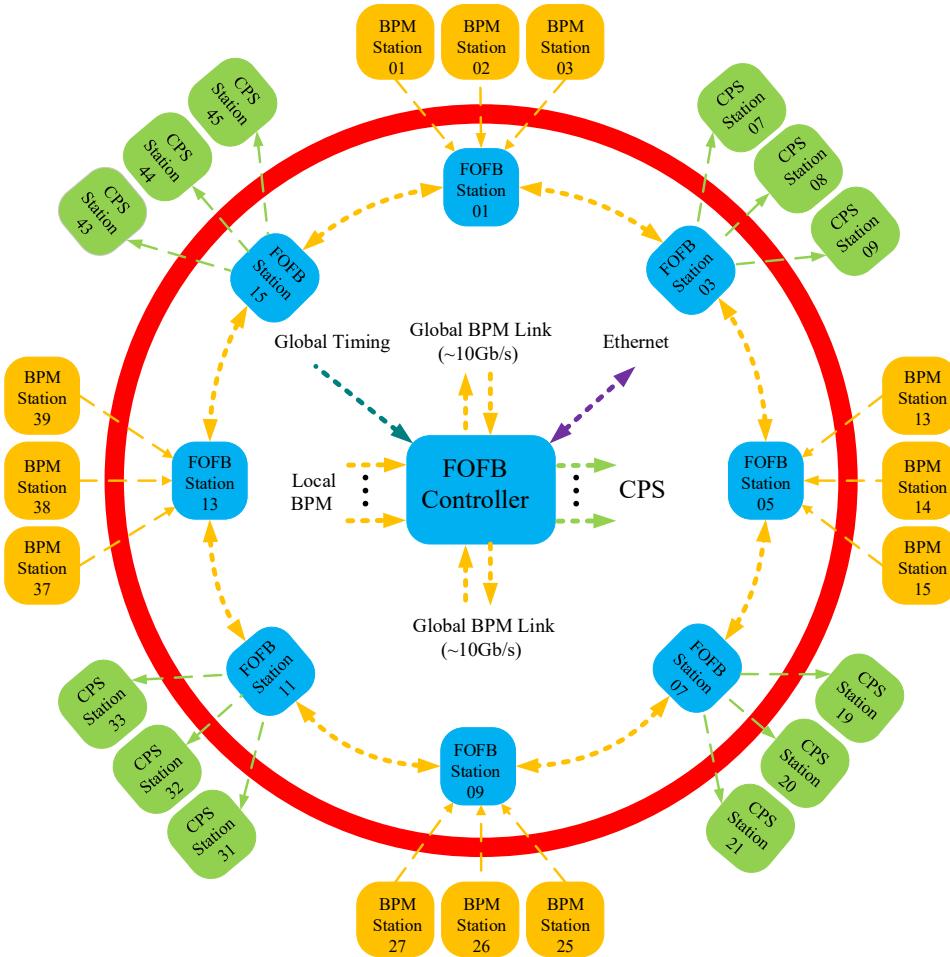


# Requirement and Considerations

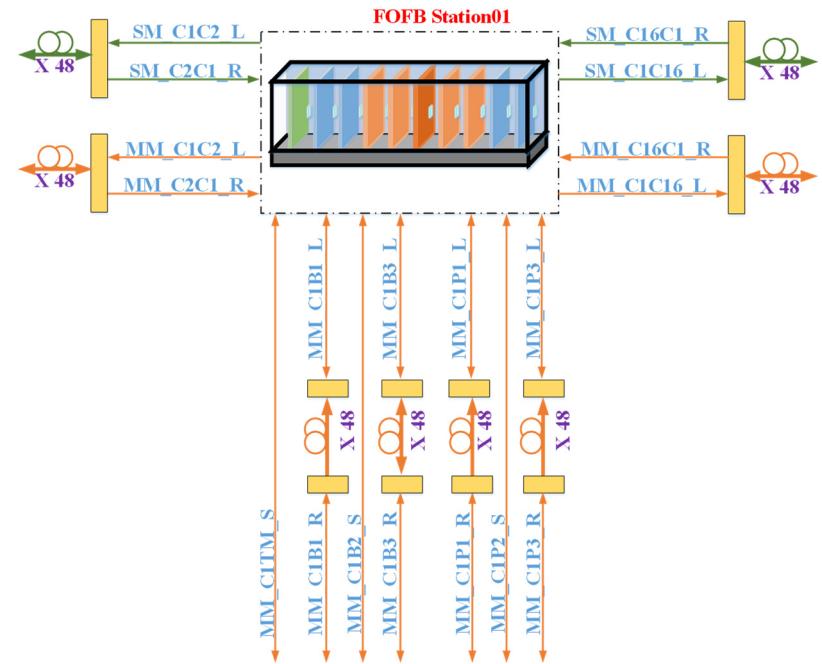
- Core chip selection : V7 from Xilinx.
- Clock frequencies of logics and DSPs, up to 1 GHz frequency is desired, at least 500 MHz.
- GTH transceivers together with optical transceivers working above 10 Gb/s for global communication, and above 5 Gb/s for BPM data collection. Multi channels will be used.
- Global timing synchronized data acquisition, transmission and logics.
- Cable routing around the ring to minimize delay.
- Parallel data transmission to PS controllers to minimize delay.
- Ripple, effective resolution, accuracy and stability of the power supplies are very important.
- Parameters consistency for the fast correctors, power supplies and vacuum chambers are very important. The same, the best.



# Architecture



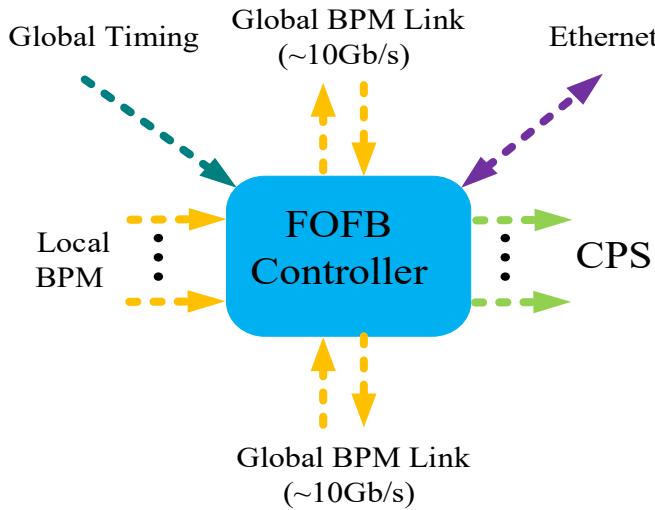
- 16 sub-stations
- 3\*12 BPMs
- 3\*8 fast correctors



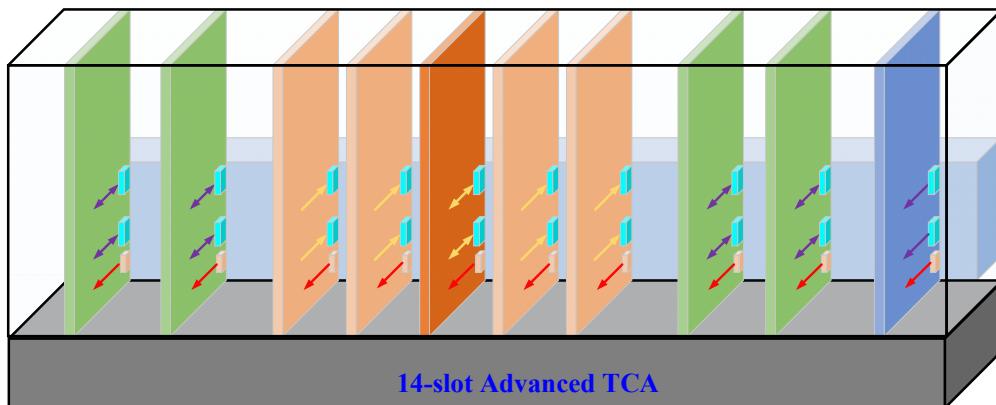
576 BPMs @192 fast corrector in both horizontal and vertical directions!



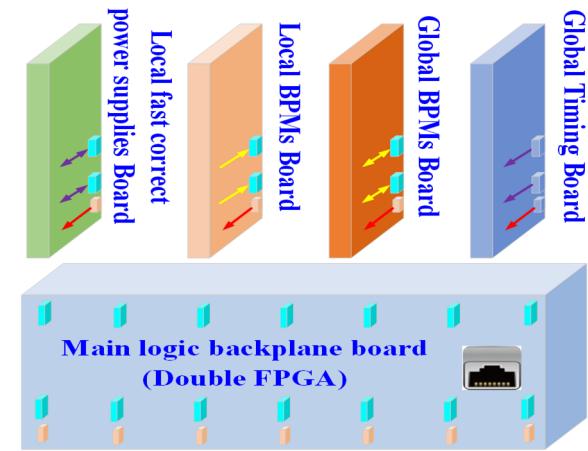
# Architecture



- 1 main logic backplane board
- 3 front boards for local BPMs
- 1 front boards for XBPM
- 1 front boards for global BPMs
- 4 front boards for local fast corrector power supplies
- 1 front boards for global Timing



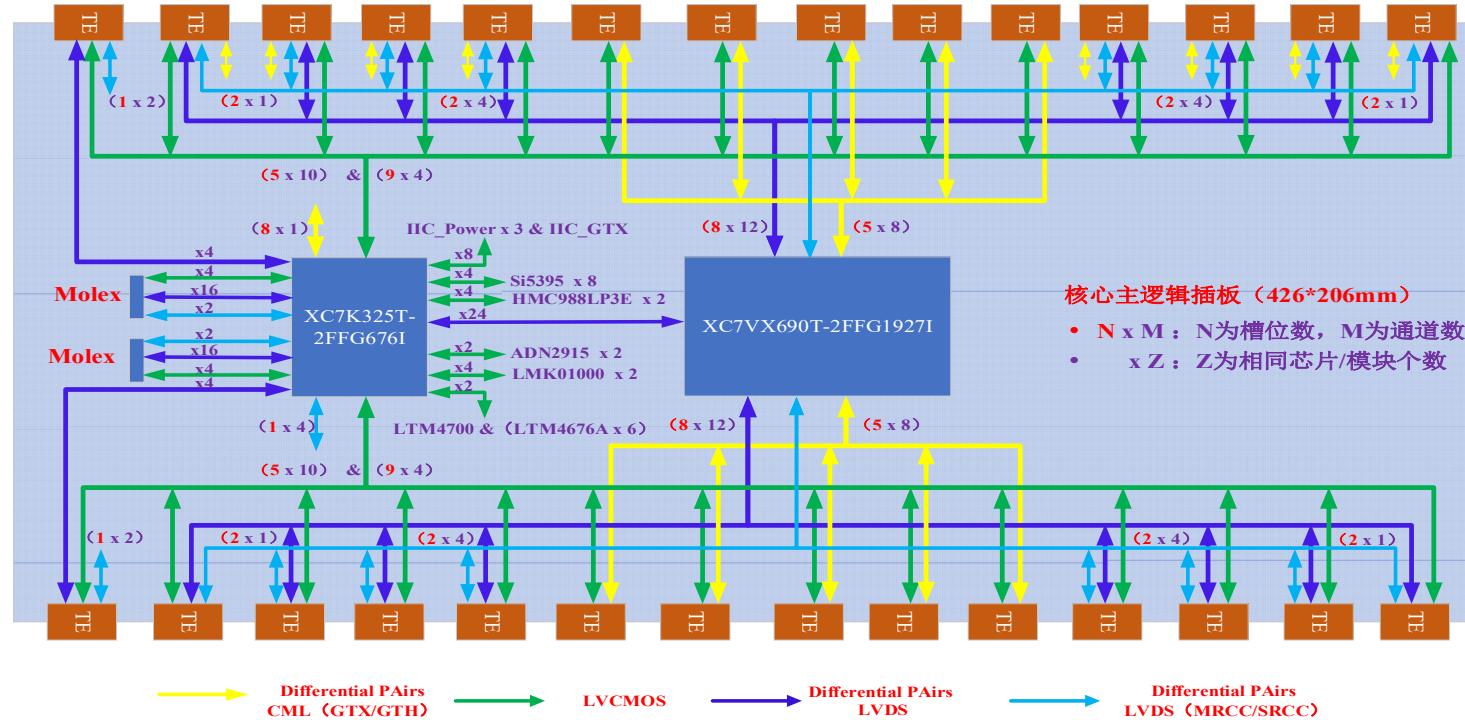
Legend:  
■ high-speed signal connector(TE)  
■ power supply connector(TE )  
→ power supply( both +12V and 3V3)  
↔ LVDS  
↔ GTH





# Main Logic Backplane Board

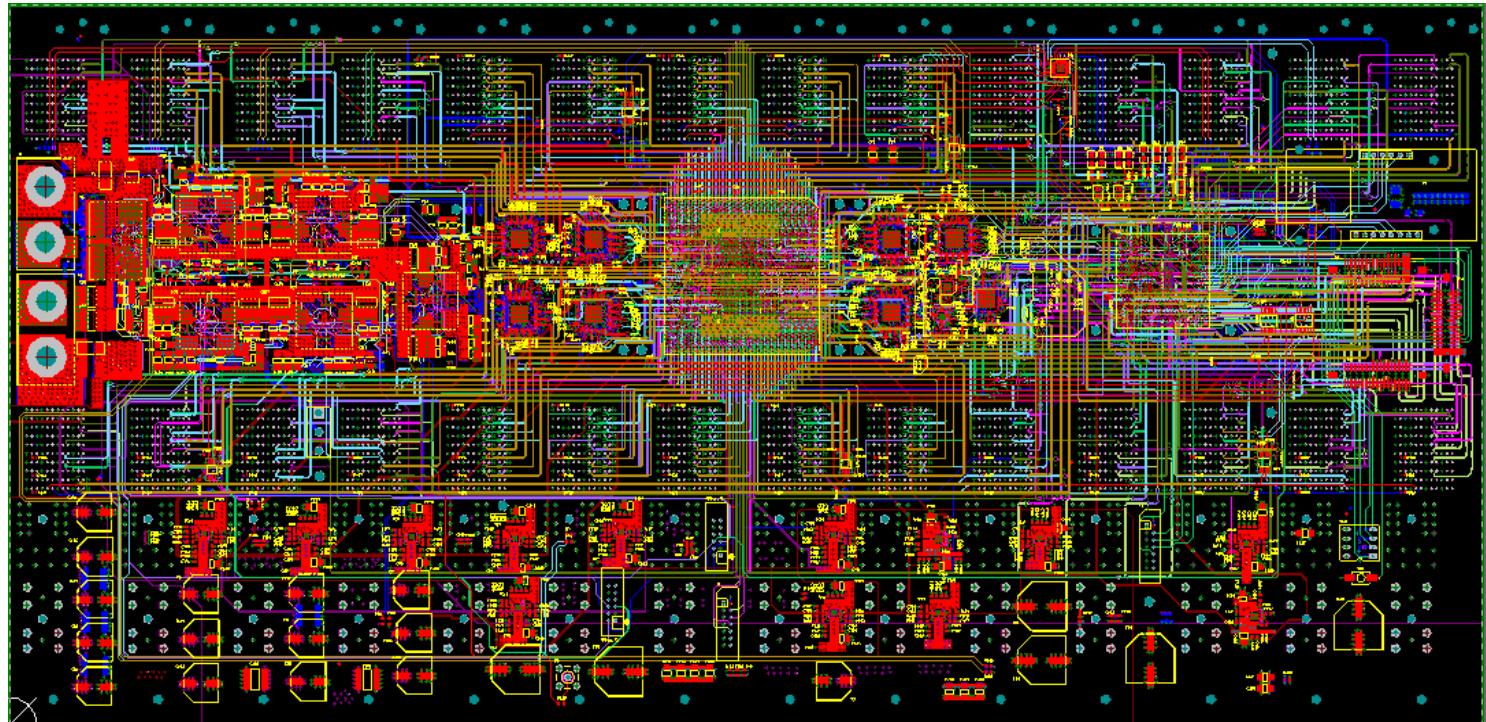
- FPGA chip: Xilinx/XC7VX690T
- High-speed: 80 channels of GTH transceiver @10 Gb
- Clock: embedded timing / on-board 100 MHz crystal clock / LEMO clock
- LVDS: 14 slots @20 channels
- Ethernet: W5500iso





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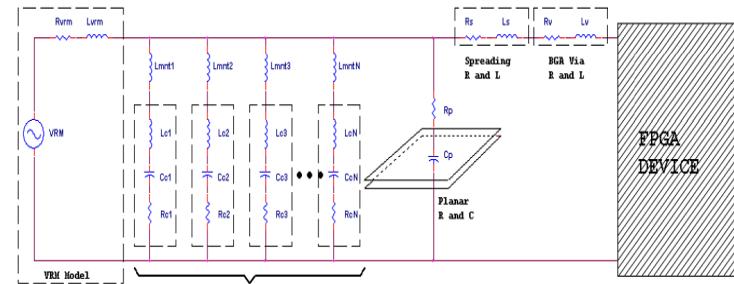


# Main Logic Backplane Board

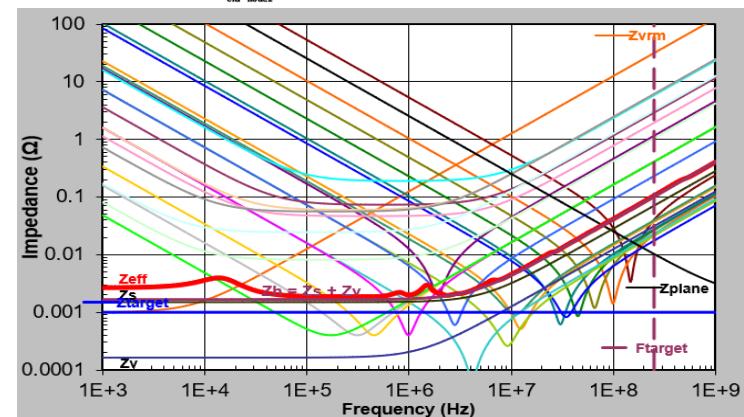
◆ Power Integrity:

considered such as the power stack and its division scheme, copper foil current carrying, ripple suppression and other design elements under the condition of transient current (about 100 A, 1 V@3%).

Board Layers And Colors		Show / Hide	View Options		Transparency
Signal Layers (S)	Color	Show	Internal Planes (P)	Color	Show
Top Layer (T)		<input checked="" type="checkbox"/>	Layer 2 (G)		<input checked="" type="checkbox"/>
Layer 3 (2)		<input checked="" type="checkbox"/>	Layer 4		<input checked="" type="checkbox"/>
Layer 5 (3)		<input checked="" type="checkbox"/>	Layer 6		<input checked="" type="checkbox"/>
Layer 7 (4)		<input checked="" type="checkbox"/>	Layer 8		<input checked="" type="checkbox"/>
Layer 9 (1)		<input checked="" type="checkbox"/>	Layer 10		<input checked="" type="checkbox"/>
Layer 14 (5)		<input checked="" type="checkbox"/>	Layer 11		<input checked="" type="checkbox"/>
Layer 16 (6)		<input checked="" type="checkbox"/>	Layer 12		<input checked="" type="checkbox"/>
Layer 18 (7)		<input checked="" type="checkbox"/>	Layer 13		<input checked="" type="checkbox"/>
Layer 20 (8)		<input checked="" type="checkbox"/>	Layer 15		<input checked="" type="checkbox"/>
Bottom Layer (B)		<input checked="" type="checkbox"/>	Layer 17		<input checked="" type="checkbox"/>
			Layer 19		<input checked="" type="checkbox"/>
			Layer 21		<input checked="" type="checkbox"/>



Target Impedance	Units	Value
Supply Voltage (Min)	V	1
I max	A	100
Transient Current	%	50
Vripple (+/-)	%	5
Frequency target	MHz	250
Ztarget = ΔV / ΔI	Ω	0.0010





# Main Logic Backplane Board

## ◆ Signal Integrity:

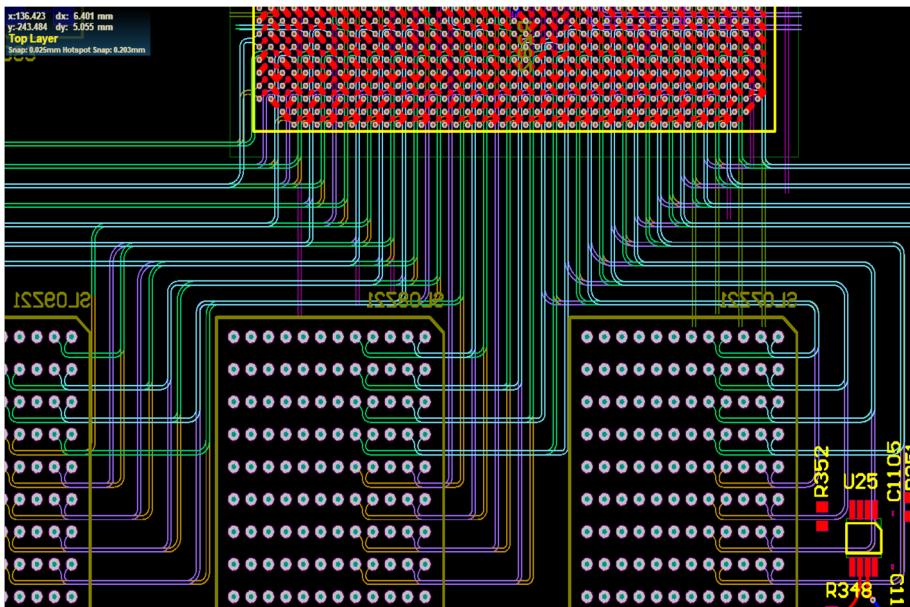
systematically studied for the characteristic impedance continuity of high-speed signals, via schemes, return path rules, nearby compensation principles, and minimizing inter-layer switching.



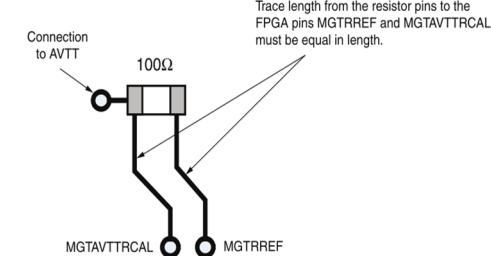
G-S-S-G优化模式



Signal Via + Back Drill



GTH



Recommend

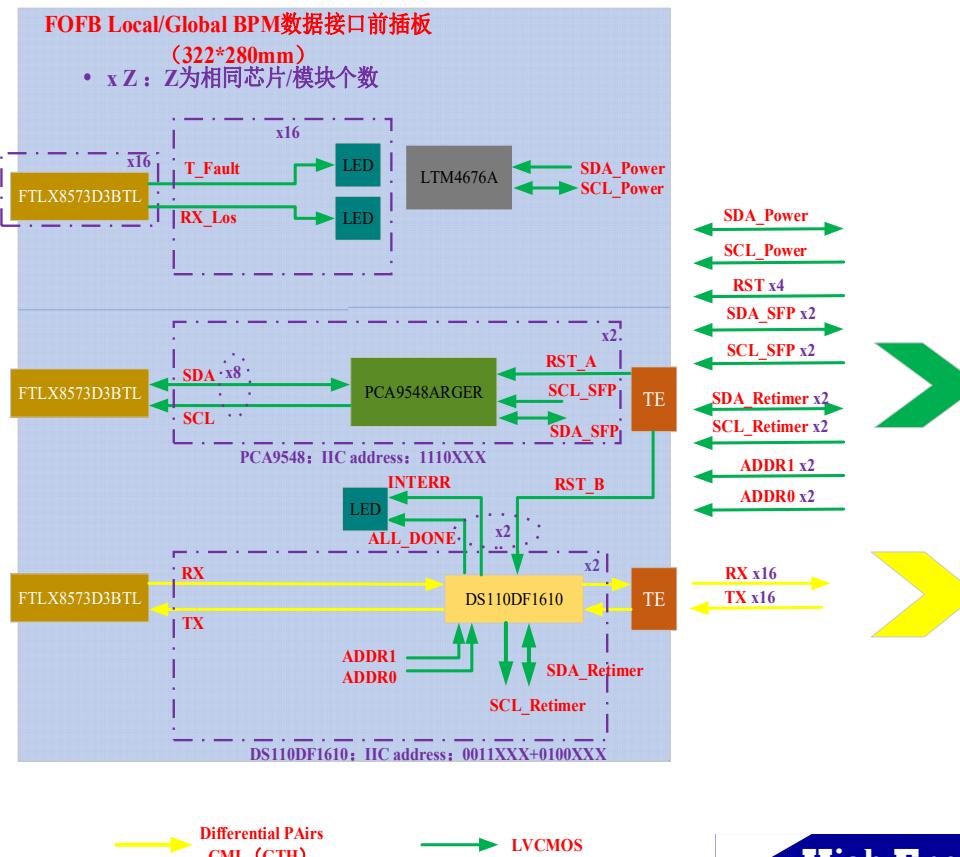


0Ω



# Front Board

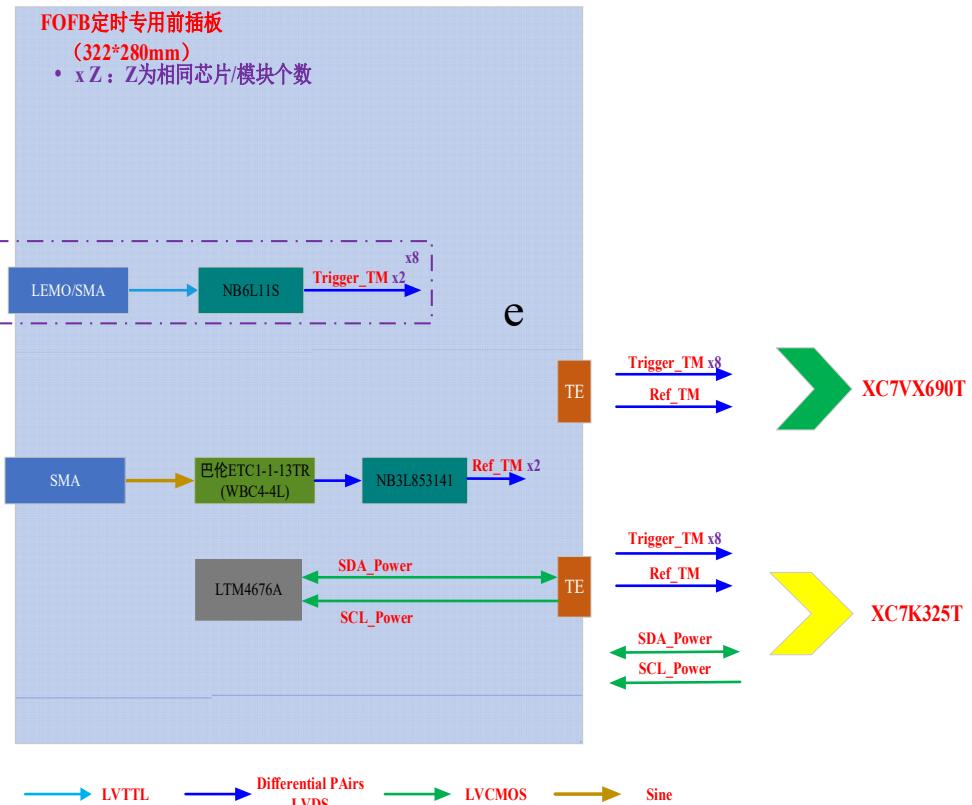
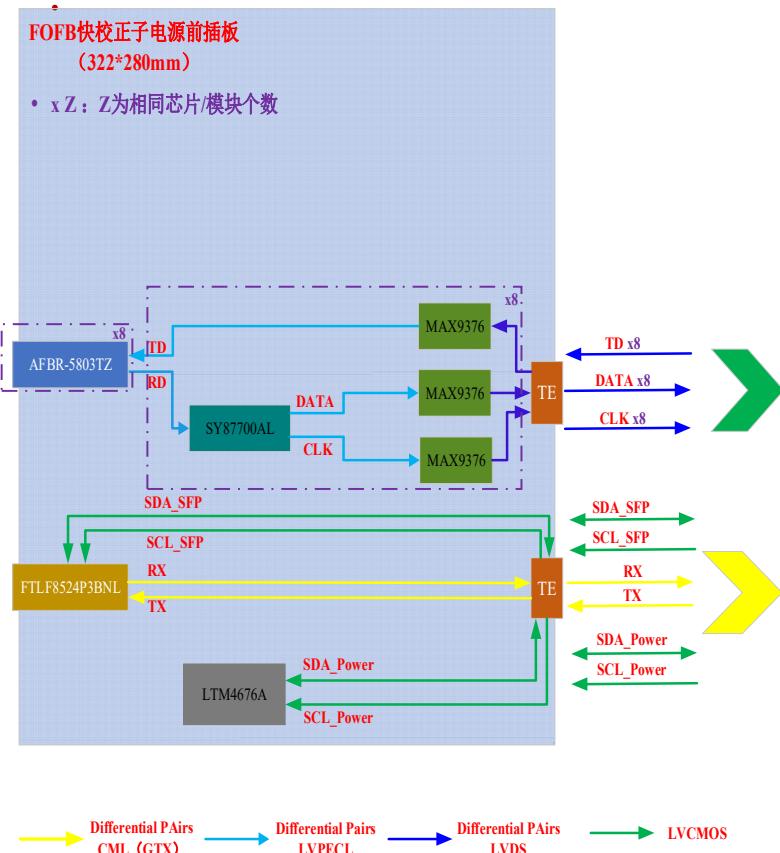
- ◆ collect 3\*12 groups of 32 bit effective data, the rate is about 2.38 Gb/s
- ◆ transmit the BPMs data, the rate is about 9.5 Gb/s
- 





# Front Board

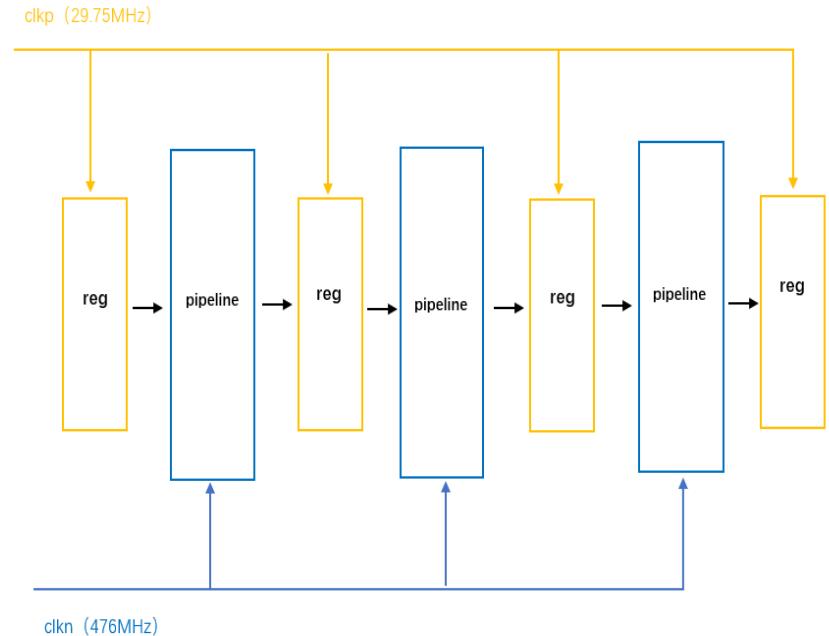
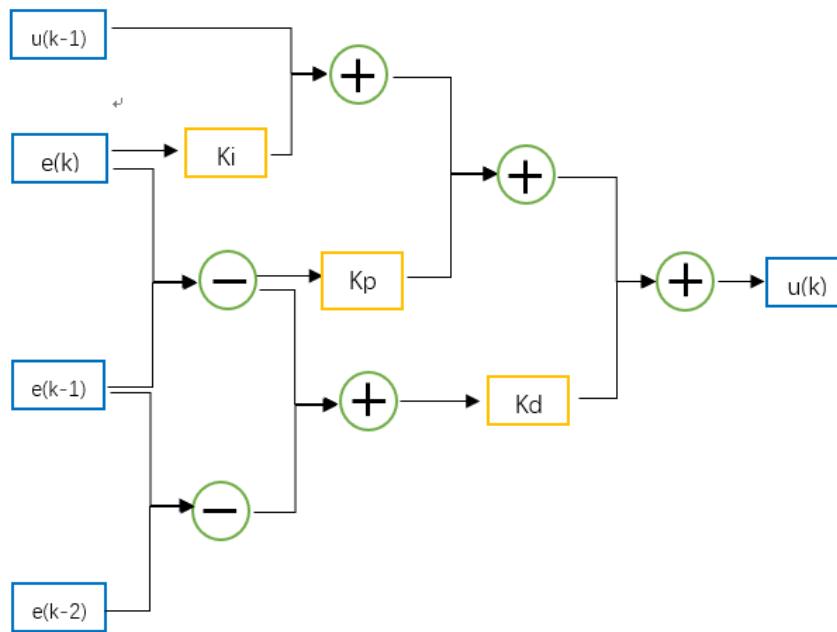
- ◆ set 3\*8 groups of current for fast corrector power supply, the rate is 50 Mb/s
- ◆ receive global timing for synchronization





# Logic development

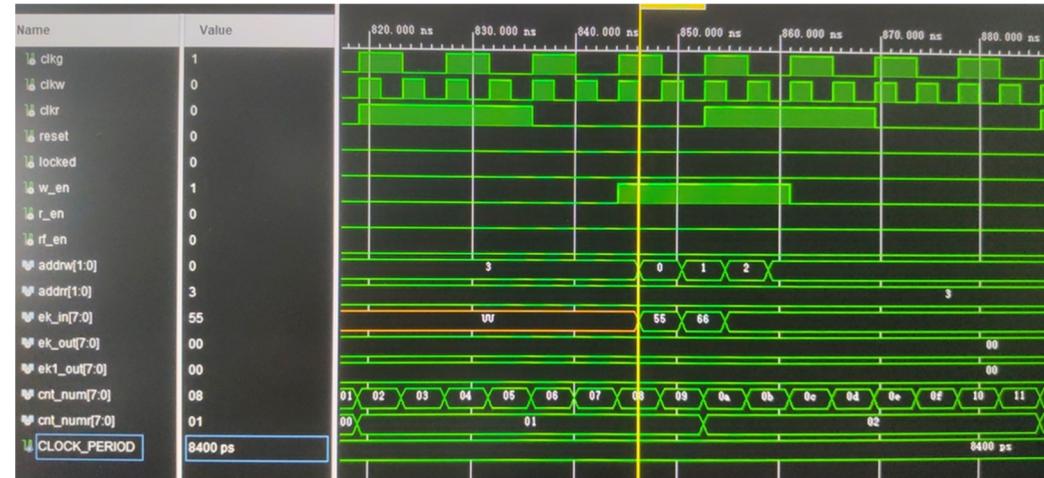
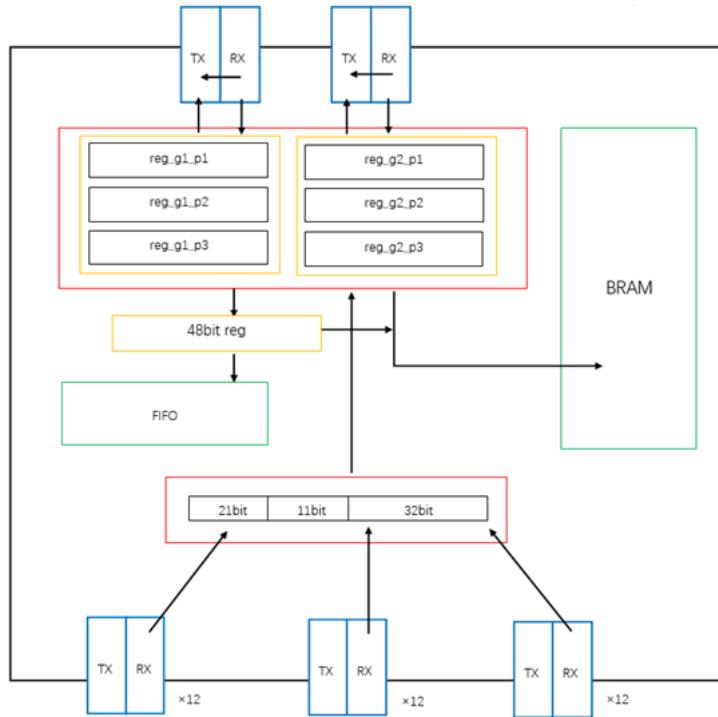
- ◆ pipeline design
- ◆ accurately control the data to reach a certain position at a certain time
- ◆ reduce latency





# Logic development

- ◆ BRAM is used in the memory module design
- ◆ ensure that the data is written and read in one clock cycle
- ◆ reduce latency.

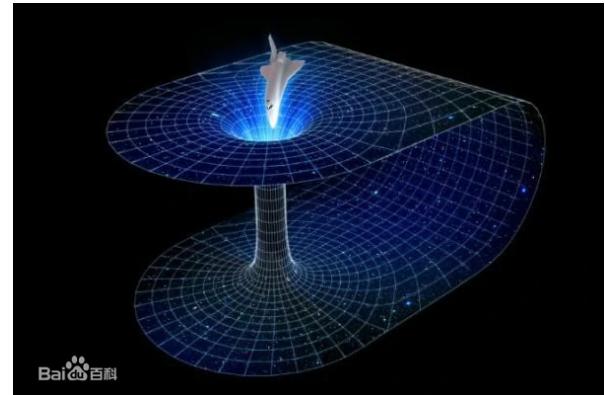




# Time Consumption Estimate

- Global optical cable delay :  $\sim 5\mu\text{s}$  for  $\sim 1\text{km}$  cables.
- Serialization/Deserialization for half the ring :  $\sim 2\mu\text{s}$  for 16 nodes.
- Global data packets transmission :  $\sim 1\mu\text{s}$ .
- Matrix calculation :  $\sim 2\mu\text{s}$ .

• • •   • • •



minimize latency as much as possible



# Schedule

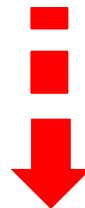
- Controllable, Orderly, and Steady!

Data	Main Mission
Apr. 1	Complete the design of all schematic
Oct. 1	Complete the design of all PCB
Dec. 1	Started joint debugging of firmware
Feb. 1	Preliminary completion of all the functional of requirements



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# Summary

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- Preliminary design and simulation results have been carried out till now
- A bandwidth of 500 Hz can be possibly achieved, even 800 Hz
- Balance among performance, cost, difficulty, complexity, reliability, availability, scalability and maintainability.
- Tight cooperation among all related systems is the key to success



# Thanks for your attention!



CSNS



HEPS